

ES3AF~ES3JF

Rev.A May.-2025

5 Ø / Descriptions

Surface Mount Superfast Recovery Rectifier, Reverse Voltage: 50 to 600V, Forward Current: 3A, SMAF thin package.

/ " / Features

Glass Passivated Chip Junction " Superfast reverse recovery time " Lead free in comply with EU R 2011/65/EU directives " For surface mounted applications, HF Product.

— ÷ / Applications

General purpose.

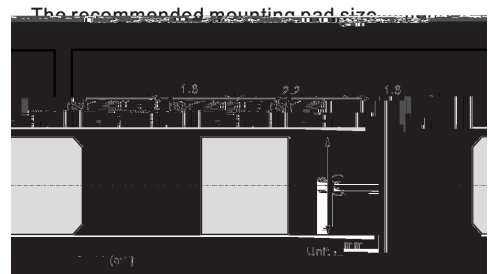
^ W] Ô• / Equivalent Circuit



Û- æ / Pinning



PIN	DESCRIPTION
1	Cathode
2	Anode



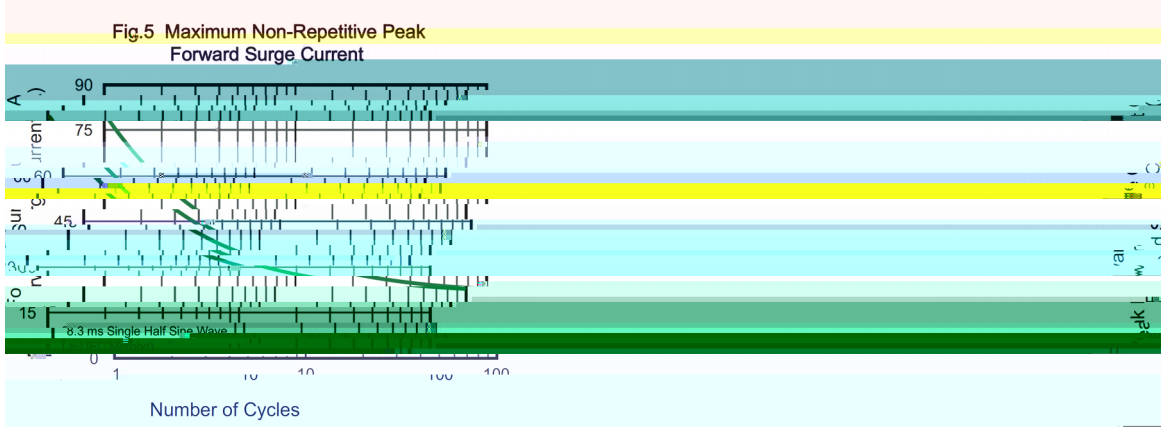
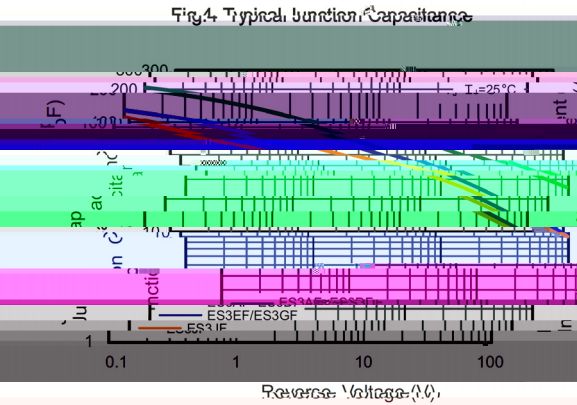
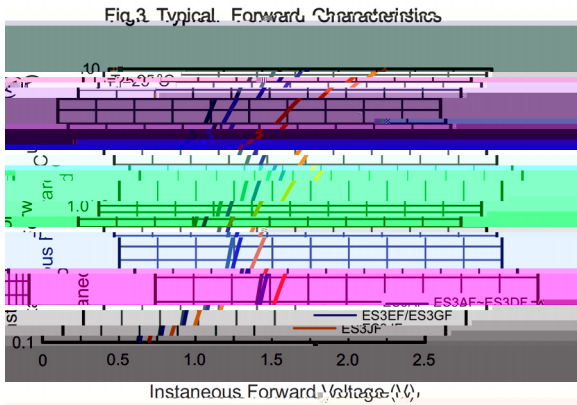
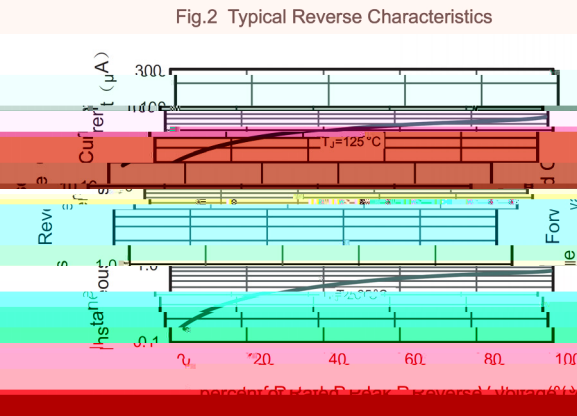
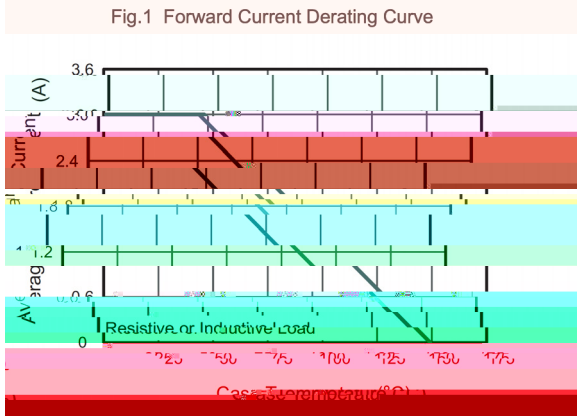
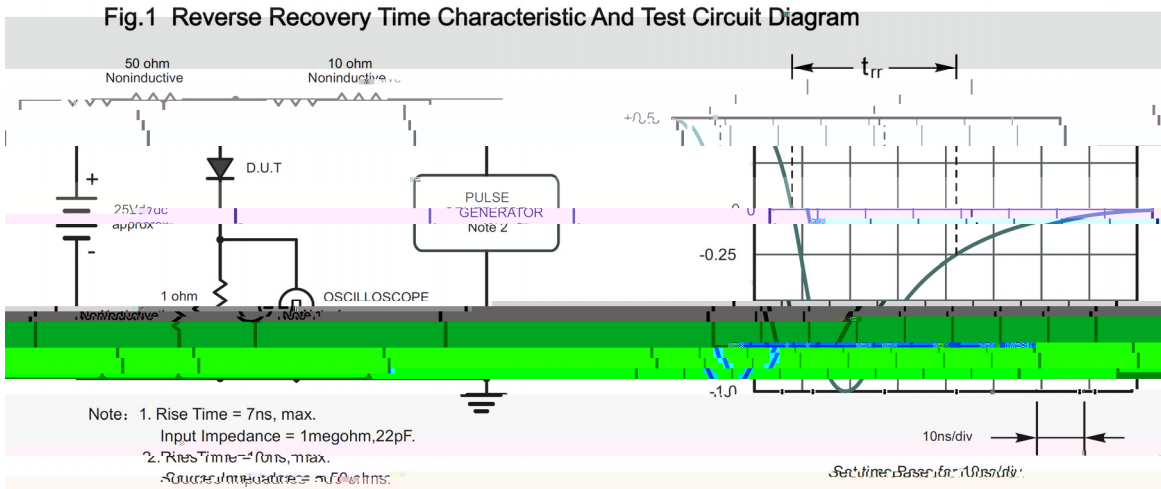
, M V / Marking

See Marking Instructions.

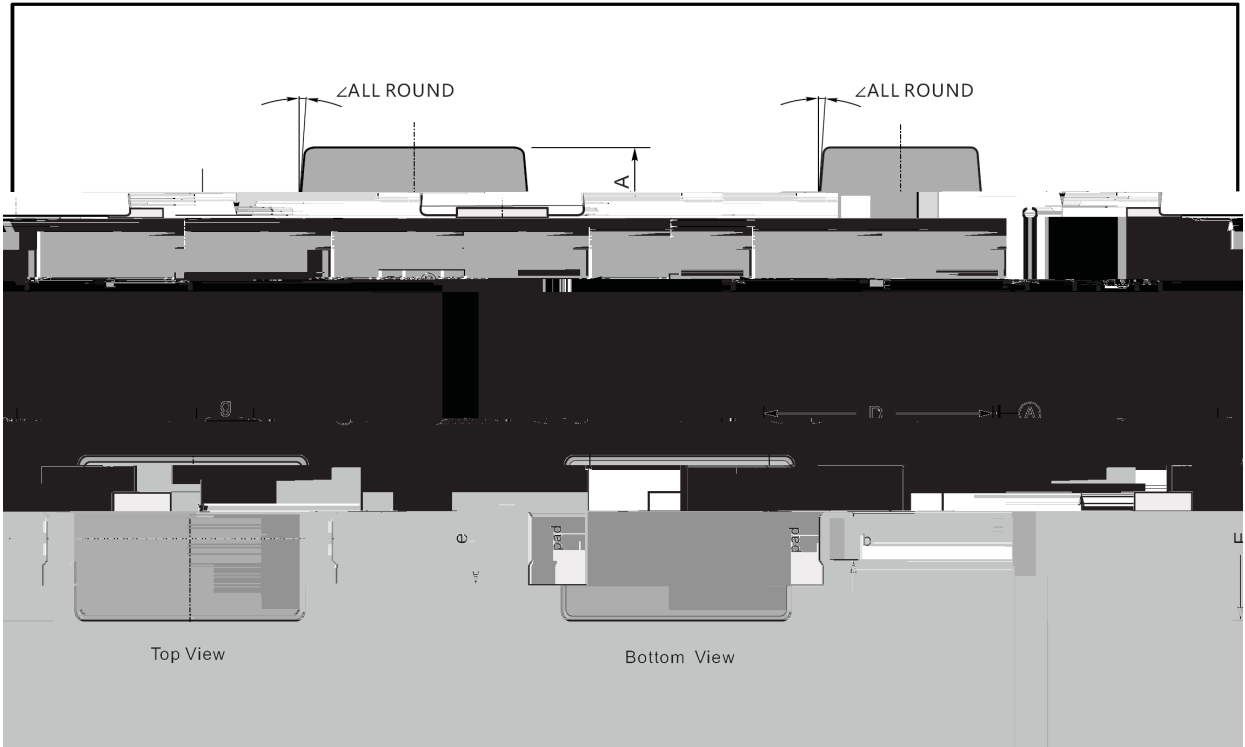
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	@	Z	Rating	% y
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Electrical Characteristic Curve



Ø/ =) ☺ / Package Dimensions



	A	C	D	E	e	g	H _E	b	Δ	UNIT	
max	1.2	0.20	3.7	2.7	1.6	1.2	4.9	1.05			
				mm	min	0.9	0.12	3.3	2.4	1.3	0.8
5	7°				max	47	7.9	146	106	63	47
				mil	min	35	3.17	133	26.4	51	21
											193
											4

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蓝箭电子
BLUE ROCKET ELECTRONICS

DATA SHEET

WD t ϕ (x /) / : K S V K X G Z [X K 6 X U L O R K L U X / 8 8 K L R U] 9 U R J K X O

" ϕ y

1o ~ %o 150 %180 - k 60 %90sec;

2o Q 245 r5 - k 4 Ò 5 r0.5sec;

3o D N ò i ÒO , 2 %10 - /sec.

Note:

1.Preheating:150~180 - , Time:60~90sec.

2.Peak Temp.:245 r5 - , Duration:5 r0.5sec.

3. Cooling Speed: 2~10 - /sec.

ˆD /Cª p fl »] / Resistance to Soldering Heat Test Conditions

605 r5 - (/ -5.7(Packagling)24286(SPEC.()J/T7 1 Tf03.4485 32.3713 TD.0004 Tc-35.65309:6025130